## **DISCRETE SEMICONDUCTORS**

# DATA SHEET

# **PDTC143Z series** NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

Product specification Supersedes data of 2004 Apr 06 2004 Aug 16





### PDTC143Z series

#### **FEATURES**

- Built-in bias resistors
- · Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

#### **APPLICATIONS**

- · General purpose switching and amplification
- · Inverter and interface circuits
- · Circuit driver.

### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	TYP.	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	_	50	V
Io	output current (DC)	_	100	mA
R1	bias resistor	4.7	_	kΩ
R2	bias resistor	47	_	kΩ

#### **DESCRIPTION**

NPN resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

#### **PRODUCT OVERVIEW**

TYPE NUMBER	PACE	KAGE	MARKING CODE	DND COMPLEMENT	
I TPE NUMBER	PHILIPS	EIAJ	MARKING CODE	PNP COMPLEMENT	
PDTC143ZE	SOT416	SC-75	38	PDTA143ZE	
PDTC143ZEF	SOT490	SC-89	53	PDTA143ZEF	
PDTC143ZK	SOT346	SC-59	18	PDTA143ZK	
PDTC143ZM	SOT883	SC-101	E3	PDTA143ZM	
PDTC143ZS	SOT54 (TO-92)	SC-43	TC143Z	PDTA143ZS	
PDTC143ZT	SOT23	_	*18 <sup>(1)</sup>	PDTA143ZT	
PDTC143ZU	SOT323	SC-70	*54 <sup>(1)</sup>	PDTA143ZU	

#### Note

<sup>1. \* =</sup> p: Made in Hong Kong.

<sup>\* =</sup> t: Made in Malaysia.

<sup>\* =</sup> W: Made in China.

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

## PDTC143Z series

### SIMPLIFIED OUTLINE, SYMBOL AND PINNING

TYPE NUMBER	CIMPLIFIED OUTLINE AND CVMDOL	PINNING		
TYPE NUMBER	SIMPLIFIED OUTLINE AND SYMBOL	PIN	DESCRIPTION	
PDTC143ZS	1 R1 R2 R2 R2 R3 RAM364	1 2 3	base collector emitter	
PDTC143ZE PDTC143ZEF PDTC143ZK PDTC143ZT PDTC143ZU	Top view  Top view  Top view  Top view	1 2 3	base emitter collector	
PDTC143ZM	2 R1 R2 R2 Dottom view MHC506	1 2 3	base emitter collector	

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

## PDTC143Z series

#### **ORDERING INFORMATION**

TYPE NUMBER		PACKAGE	
I TPE NUMBER	NAME	DESCRIPTION	VERSION
PDTC143ZE	_	<ul> <li>plastic surface mounted package; 3 leads</li> </ul>	
PDTC143ZEF	<ul> <li>plastic surface mounted package; 3 leads</li> </ul>		SOT490
PDTC143ZK	_	plastic surface mounted package; 3 leads	SOT346
PDTC143ZM	_	leadless ultra small plastic package; 3 solder lands; body $1.0 \times 0.6 \times 0.5$ mm	SOT883
PDTC143ZS	_	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTC143ZT	_	plastic surface mounted package; 3 leads	SOT23
PDTC143ZU	_	plastic surface mounted package; 3 leads	SOT323

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	50	V
V <sub>CEO</sub>	collector-emitter voltage	open base	_	50	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	10	V
VI	input voltage				
	positive		_	+30	V
	negative		_	<b>-</b> 5	V
Io	output current (DC)		_	100	mA
I <sub>CM</sub>	peak collector current		_	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C			
	SOT54	note 1	_	500	mW
	SOT23	note 1	_	250	mW
	SOT346	note 1	_	250	mW
	SOT323	note 1	_	200	mW
	SOT883	notes 2 and 3	_	250	mW
	SOT416	note 1	_	150	mW
	SOT490	notes 1 and 2	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

### Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu m$  copper strip line.

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

## PDTC143Z series

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air		
	SOT54	note 1	250	K/W
	SOT23	note 1	500	K/W
	SOT346	note 1	500	K/W
	SOT323	note 1	625	K/W
	SOT883	notes 2 and 3	500	K/W
	SOT416	note 1	833	K/W
	SOT490	notes 1 and 2	500	K/W

#### **Notes**

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60  $\mu m$  copper strip line.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = 50 V; I <sub>E</sub> = 0 A	_	_	100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = 30 V; I <sub>B</sub> = 0 A	_	_	1	μΑ
		$V_{CE} = 30 \text{ V}; I_{B} = 0 \text{ A}; T_{j} = 150 ^{\circ}\text{C}$	_	_	50	μΑ
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; I_{C} = 0 \text{ A}$	_	_	170	μΑ
h <sub>FE</sub>	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 10 \text{ mA}$	100	_	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = 5 \text{ mA}; I_B = 0.25 \text{ mA}$	_	_	100	mV
$V_{i(off)}$	input-off voltage	$I_C = 100 \mu\text{A};  V_{CE} = 5 \text{V}$	_	0.6	0.5	V
$V_{i(on)}$	input-on voltage	$I_C = 5 \text{ mA}; V_{CE} = 0.3 \text{ V}$	1.3	0.9	_	V
R1	input resistor		3.3	4.7	6.1	kΩ
R2 R1	resistor ratio		8	10	12	
C <sub>c</sub>	collector capacitance	$I_E = I_e = 0 \text{ A}; V_{CB} = 10 \text{ V};$ f = 1 MHz	_	_	2.5	pF

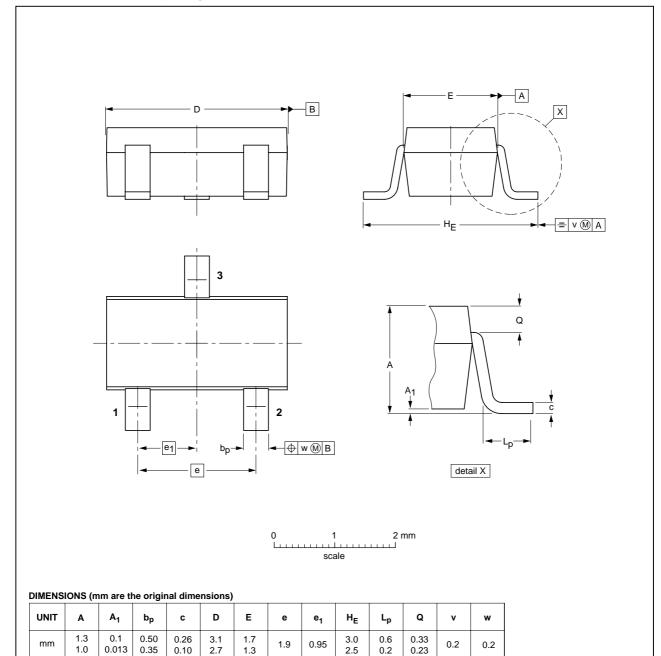
# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

## PDTC143Z series

#### **PACKAGE OUTLINES**

### Plastic surface mounted package; 3 leads

**SOT346** 

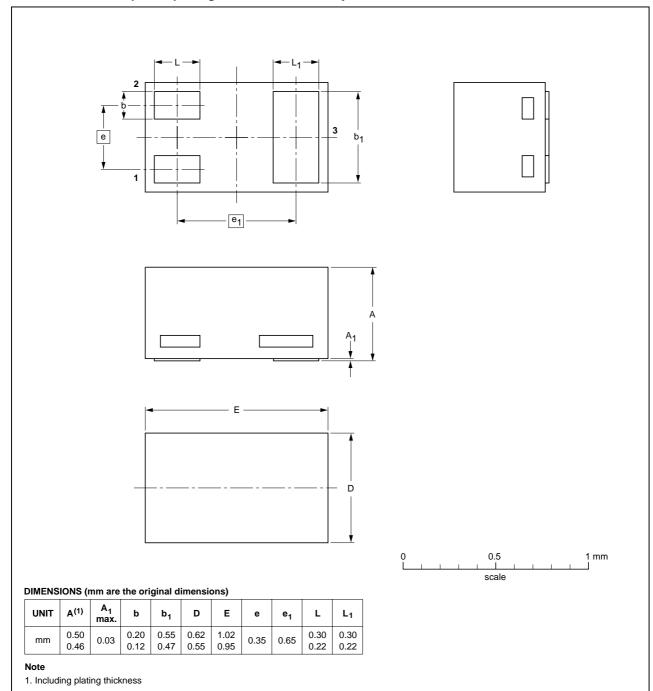


OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT346		TO-236	SC-59		98-07-17	

## PDTC143Z series

### Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

**SOT883** 



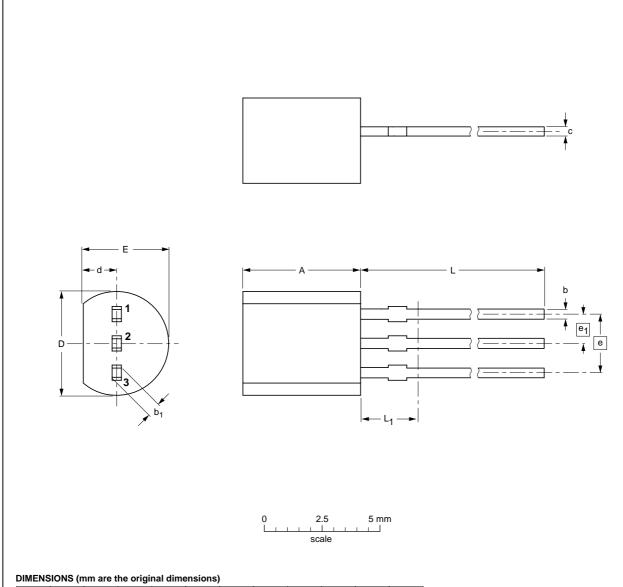
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT883			SC-101		<del>03-02-05</del> 03-04-03

# NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

## PDTC143Z series

### Plastic single-ended leaded (through hole) package; 3 leads

SOT54



UNIT	A	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max.
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5

#### Note

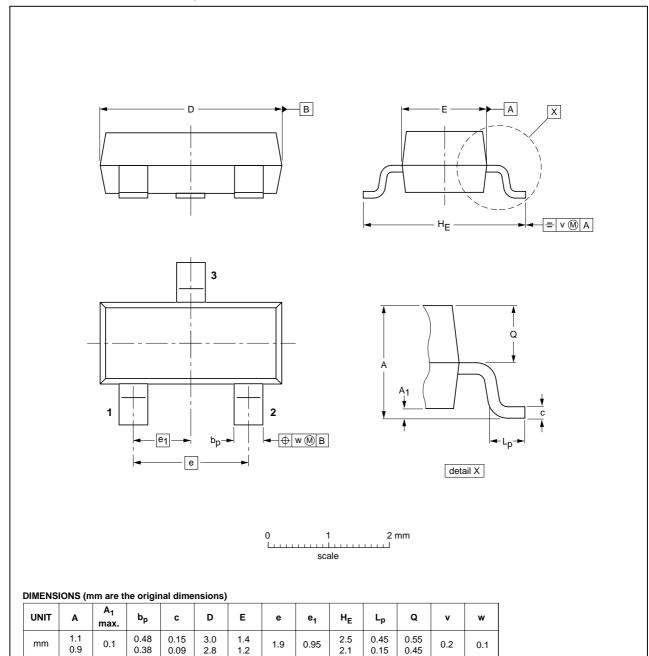
1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	1330E DATE
SOT54		TO-92	SC-43A		<del>97-02-28</del> 04-06-28

## PDTC143Z series

### Plastic surface mounted package; 3 leads

SOT23

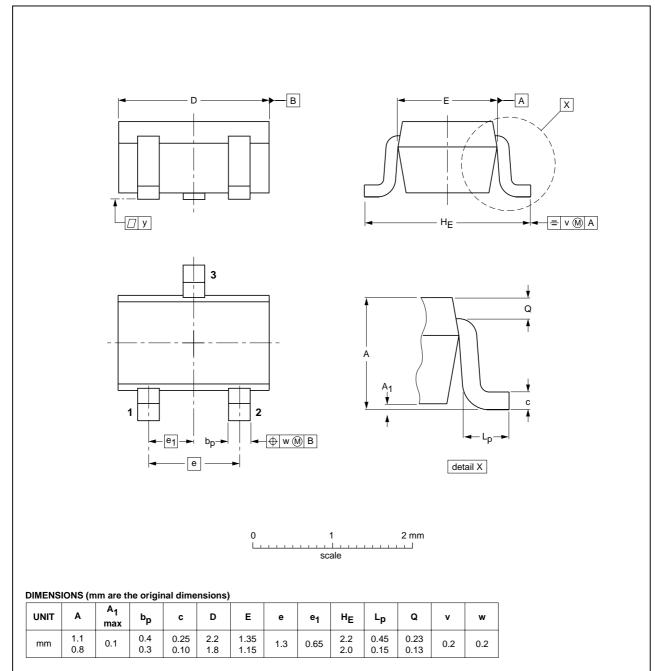


OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE	
SOT23		TO-236AB			<del>-97-02-28</del> 99-09-13	

## PDTC143Z series

### Plastic surface mounted package; 3 leads

**SOT323** 

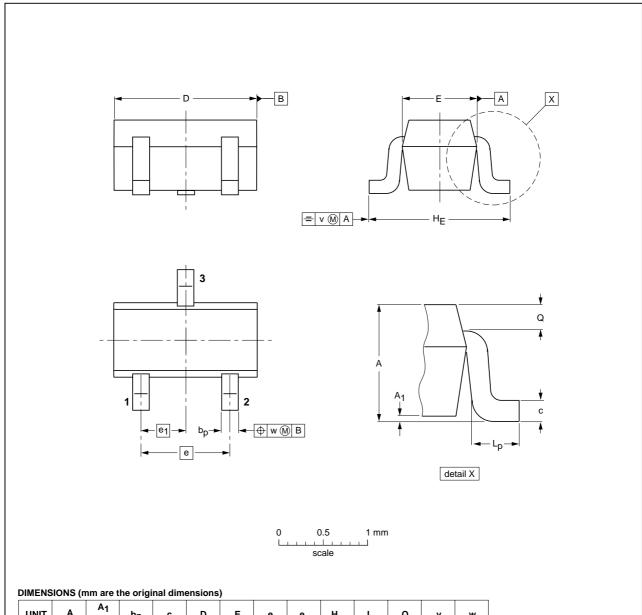


	OUTLINE VERSION		REFER	EUROPEAN	ISSUE DATE		
		IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
	SOT323			SC-70			97-02-28

## PDTC143Z series

### Plastic surface mounted package; 3 leads

**SOT416** 



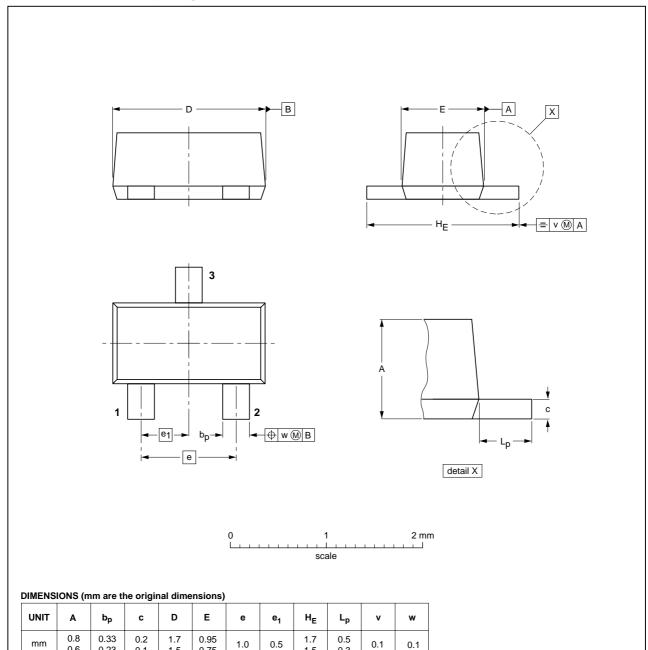
UNI	ГА	A <sub>1</sub> max	bp	С	D	E	e	e <sub>1</sub>	HE	Lp	Q	v	w
mn	0.95 0.60	0.1	0.30 0.15	0.25 0.10	1.8 1.4	0.9 0.7	1	0.5	1.75 1.45	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE		REFER	EUROPEAN	IOOUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT416			SC-75			97-02-28	

## PDTC143Z series

### Plastic surface mounted package; 3 leads

**SOT490** 



OUTLINE		REFER	EUROPEAN	IOOUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT490			SC-89			98-10-23	

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## NPN resistor-equipped transistors; R1 = 4.7 k $\Omega$ , R2 = 47 k $\Omega$

### PDTC143Z series

#### **DATA SHEET STATUS**

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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